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Apparatus for the automatic production of a series arrangement of wafer-like  
electronic parts  
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#Inventor:  
HAMURO MITSURO (JP); TABUCHI MAKOTO (JP); IMANISHI KIYOSHI (JP); HONDA FUMIO  
(US); HIGUCHI HIROKAZU (US)  
#Applicant:  
MURATA MANUFACTURING CO (JP)  
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#Abstract:  
Apparatus for the automatic production of a series arrangement containing  
electronic parts, by means of a receiving body provided with receiving orifices,  
in which electronic parts designed without junction wires are accommodated. In  
the apparatus working automatically, a band-shaped receiving body is moved  
intermittently in the longitudinal direction and wafer-like electronic parts are  
supplied successively by a feed device, specifically into each receiving orifice  
of the receiving body in the direction of transport. The receiving orifice is  
closed by a band-shaped covering strip when the part is fed in. The covering  
strip is applied to the receiving body by an applicator device, whereupon the  
series arrangement containing the electronic parts is wound onto a drum in a  
winding device.